



US00D569372S

(12) **United States Design Patent**  
**Brennwald**

(10) **Patent No.:** **US D569,372 S**

(45) **Date of Patent:** **\*\* May 20, 2008**

(54) **HEADSET**

(75) Inventor: **Joerg Brennwald**, Kiel (DE)

(73) Assignee: **Sennheiser electronic GmbH & Co. KG**, Wedemark (DE)

(\*\*) Term: **14 Years**

(21) Appl. No.: **29/276,238**

(22) Filed: **Jan. 19, 2007**

(30) **Foreign Application Priority Data**

Jul. 21, 2006 (DE) ..... 4 06 03 903

(51) **LOC (8) Cl.** ..... **14-01**

(52) **U.S. Cl.** ..... **D14/224; D14/205**

(58) **Field of Classification Search** ..... D14/149,  
D14/155, 205–206, 217, 223, 224, 251, 253,  
D14/229, 168, 137, 240; D13/107–108;  
D16/242; 320/113; 379/430–431, 446–447,  
379/450, 454, 455; 455/569.1; D10/106  
See application file for complete search history.

(56) **References Cited**

**U.S. PATENT DOCUMENTS**

D307,016 S *	4/1990	Watanabe	.....	D14/240
D322,068 S *	12/1991	Yamakawa	.....	D14/168
D328,276 S *	7/1992	Koinuma	.....	D13/107
D329,221 S *	9/1992	Khoo	.....	D13/107
D355,913 S *	2/1995	Chong	.....	D14/168
D357,016 S *	4/1995	Li et al.	.....	D14/168
D376,330 S *	12/1996	Bellomo et al.	.....	D10/106
D390,553 S *	2/1998	Beaumont et al.	.....	D14/137
D400,165 S *	10/1998	Nagele et al.	.....	D13/108
6,229,893 B1 *	5/2001	Chen	.....	379/454
D462,337 S *	9/2002	Schmidt et al.	.....	D14/149

D462,342 S *	9/2002	Polito et al.	.....	D14/224
D472,538 S *	4/2003	Chan	.....	D14/149
D496,029 S *	9/2004	Skulley et al.	.....	D14/224
D513,404 S *	1/2006	Lodato et al.	.....	D13/108
D518,477 S *	4/2006	Chen	.....	D14/223
D520,946 S *	5/2006	Nasu	.....	D13/108
D528,979 S *	9/2006	Franck et al.	.....	D13/108
D532,005 S *	11/2006	Leith	.....	D14/253
D541,793 S *	5/2007	Katsumata	.....	D14/240
D551,216 S *	9/2007	Wei	.....	D14/223

\* cited by examiner

*Primary Examiner*—Paula A Greene

(74) *Attorney, Agent, or Firm*—Reed Smith LLP

(57) **CLAIM**

The ornamental design for headset, as shown and described.

**DESCRIPTION**

FIG. 1 is a three-dimensional top view of the headset in accordance with the invention;

FIG. 2 is a three-dimensional bottom view of the headset in accordance with the invention;

FIG. 3 is a three-dimensional front view of the headset in accordance with the invention;

FIG. 4 is an isometric view of the headset in accordance with the invention;

FIG. 5 is a three-dimensional right side view of the headset in accordance with the invention;

FIG. 6 is a three-dimensional left side view of the headset in accordance with the invention; and,

FIG. 7 is a three-dimensional back view of the headset in accordance with the invention.

**1 Claim, 7 Drawing Sheets**



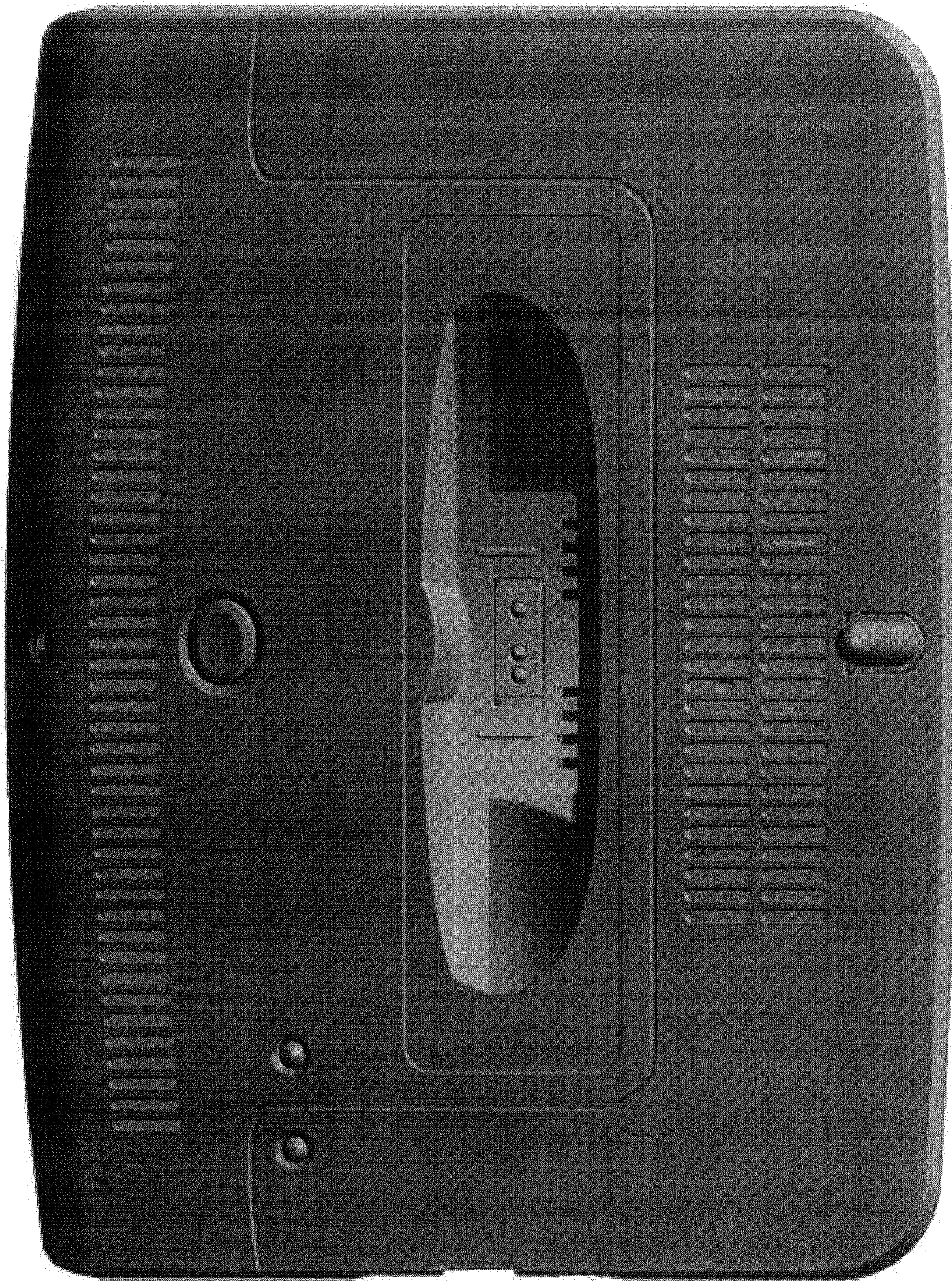


FIG. 1

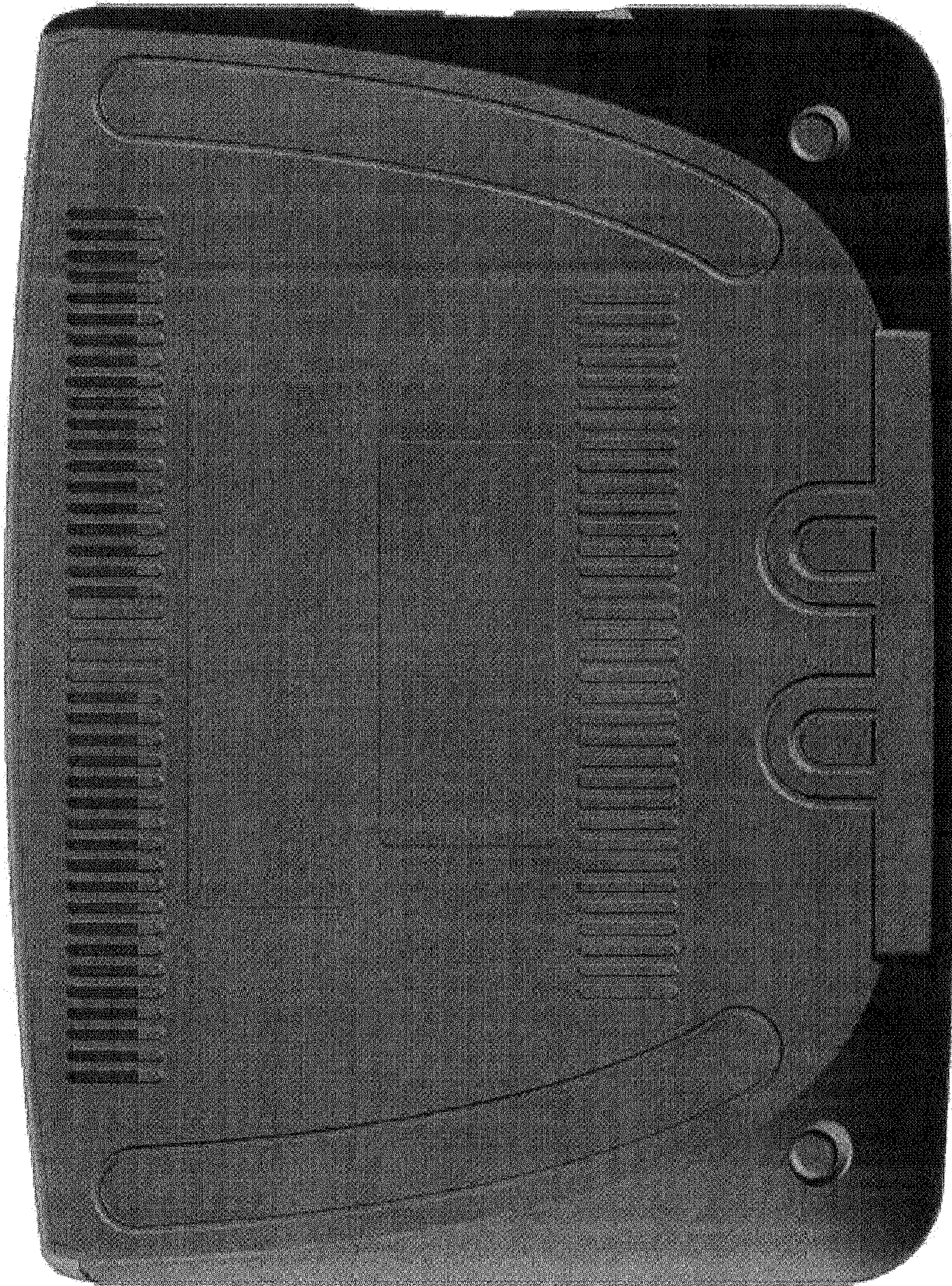


FIG. 2

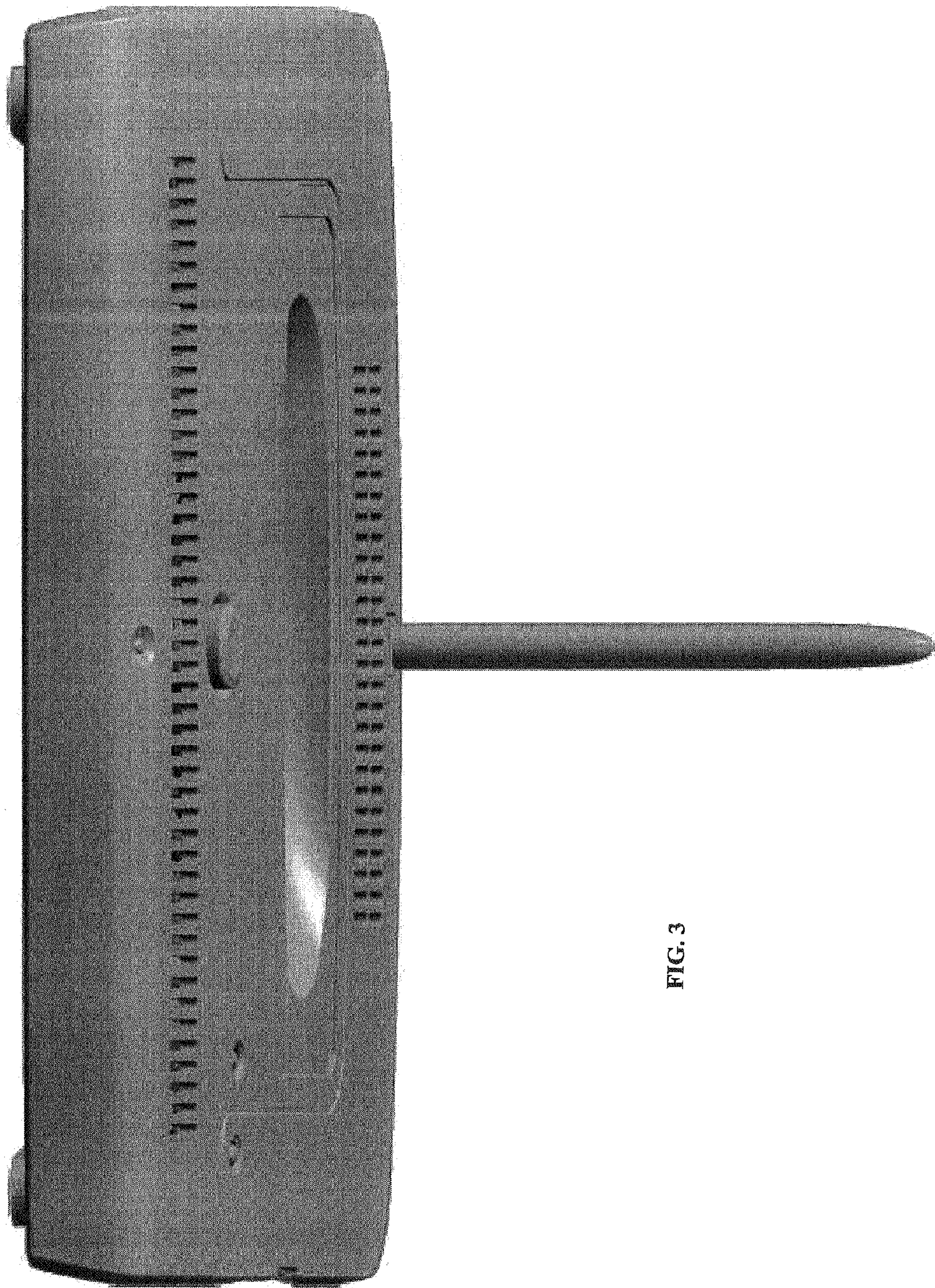


FIG. 3

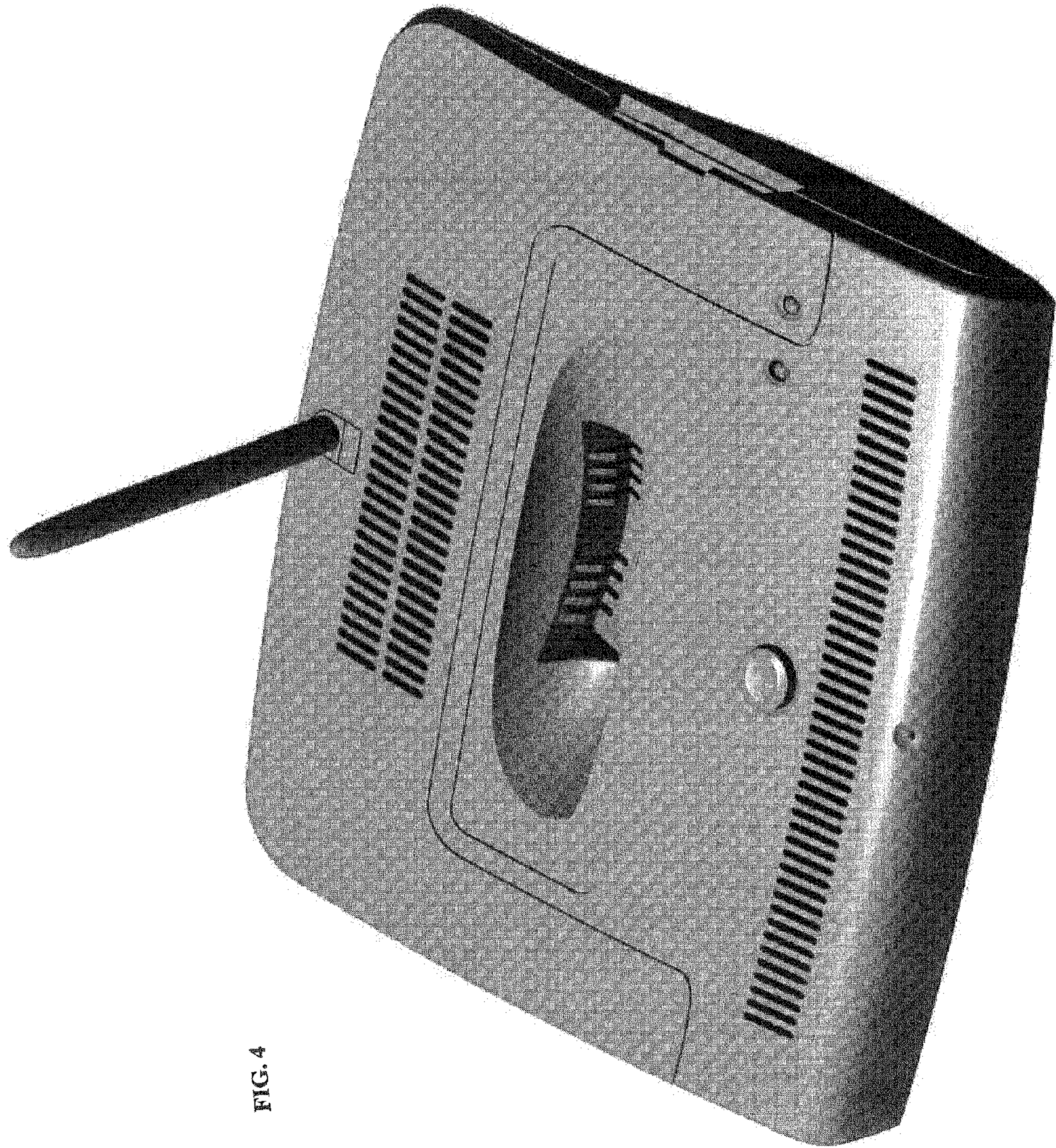


FIG. 4

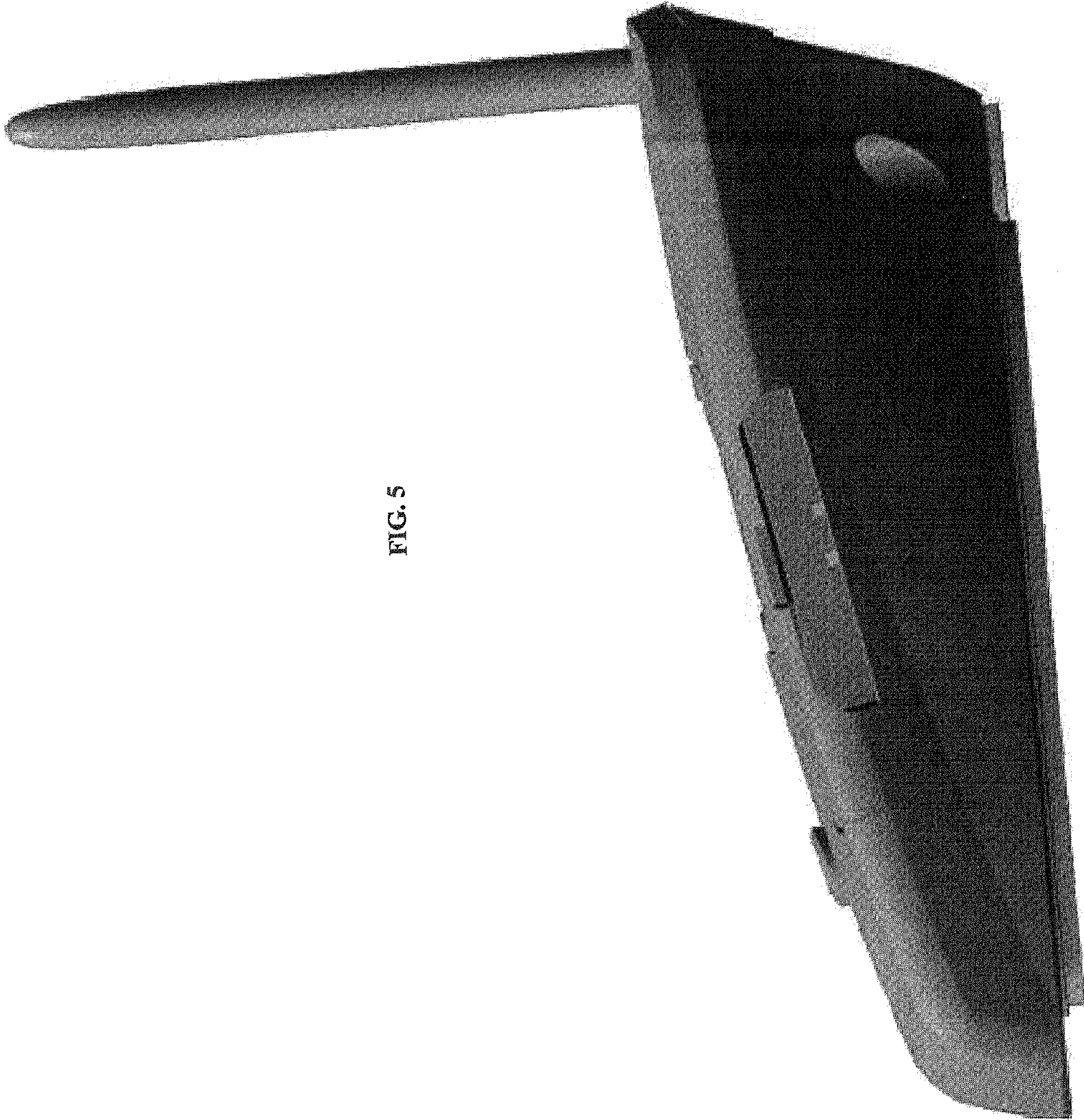


FIG. 5

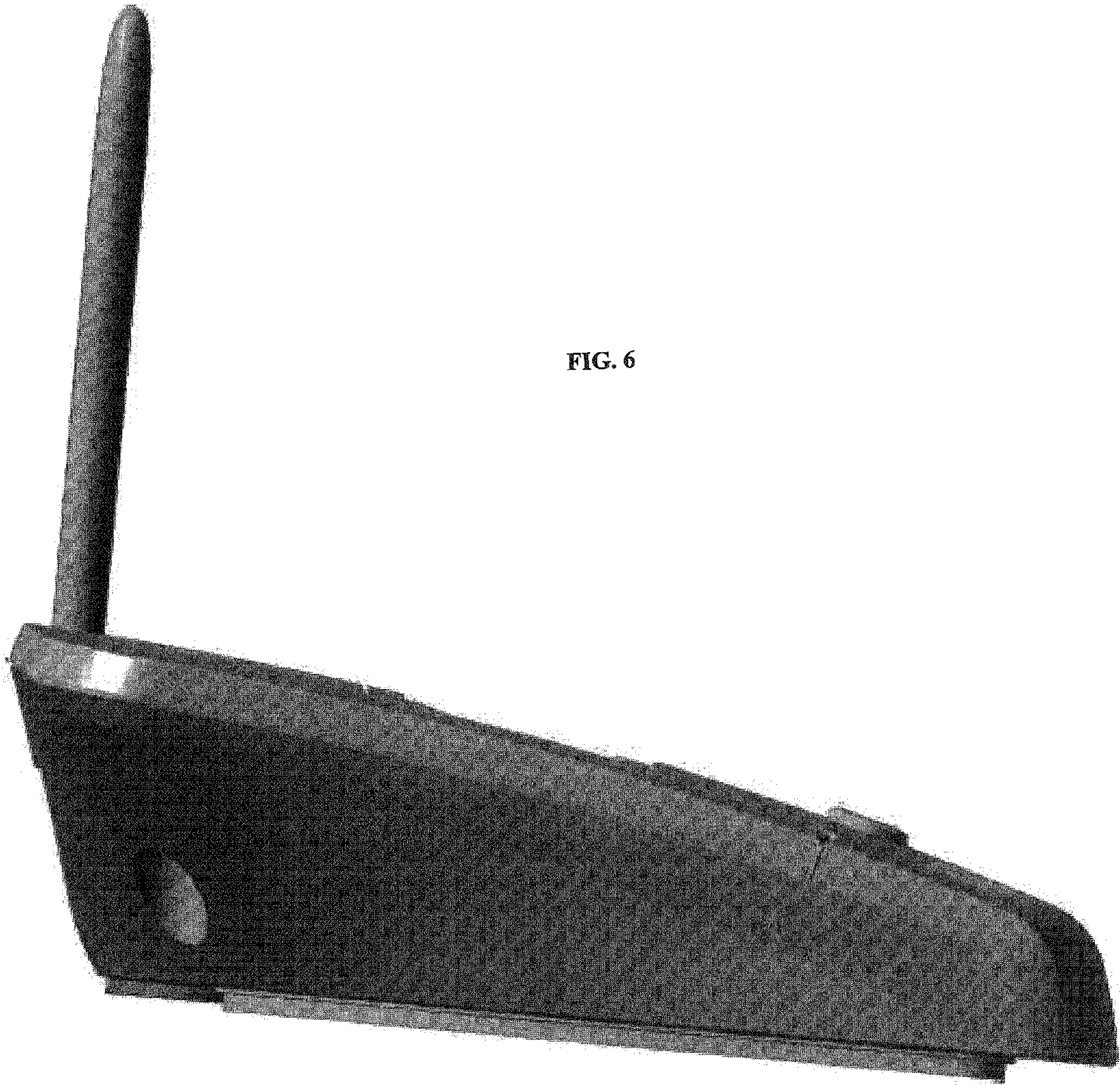


FIG. 6

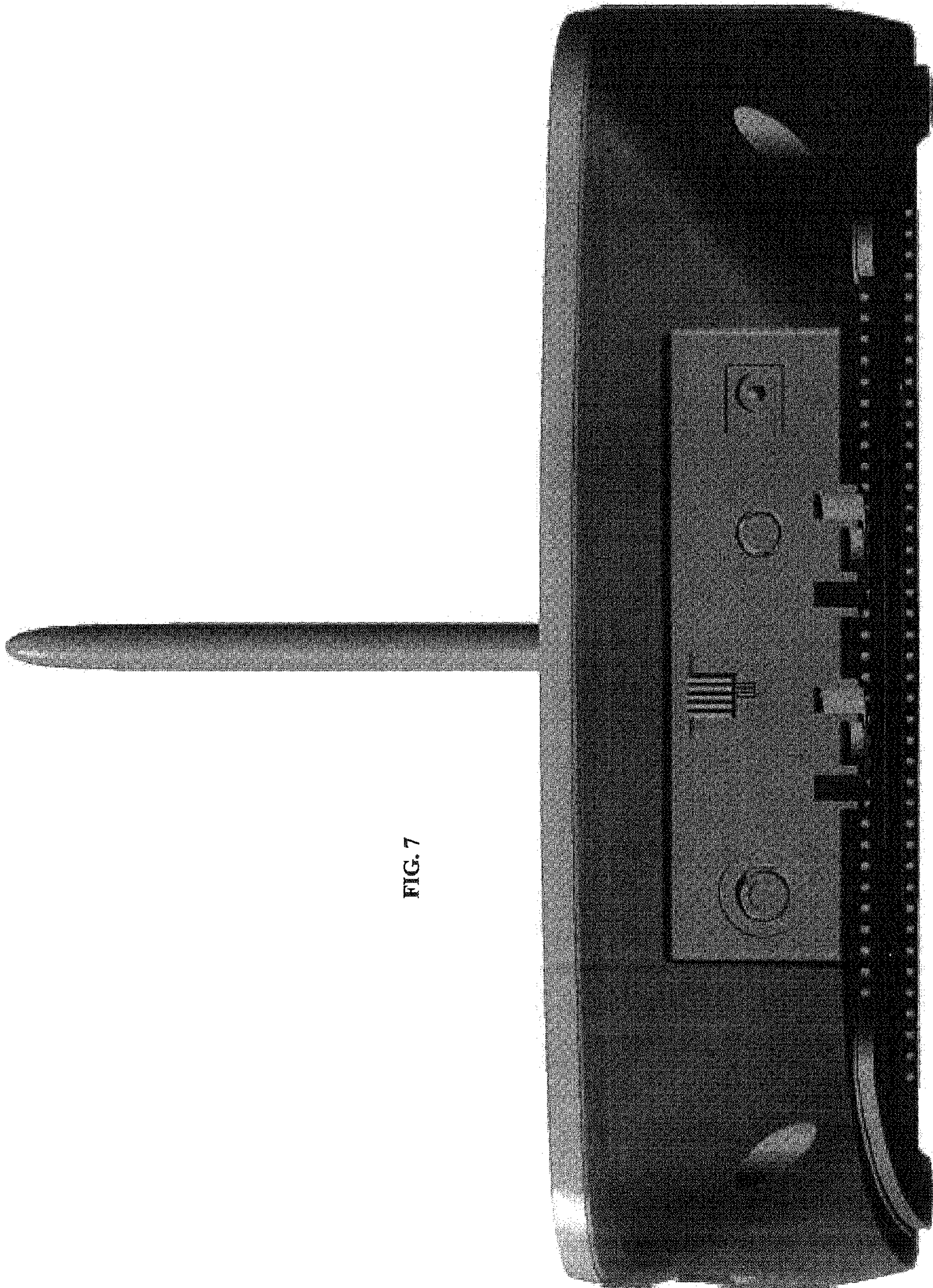


FIG. 7